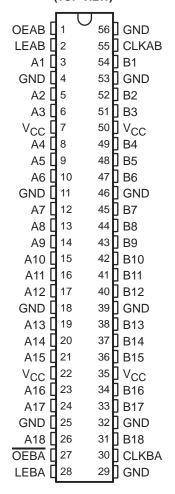
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V **Operation and Low-Static Power** Dissipation
- **Members of the Texas Instruments** *Widebus*™ Family
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- **Support Unregulated Battery Operation** Down to 2.7 V
- **UBT**[™] (Universal Bus Transceiver) **Combines D-Type Latches and D-Type** Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- Typical V_{OLP} (Output Ground Bounce) $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V **Using Machine Model** (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- **Support Live Insertion**
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes **PCB Layout**
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

SN54LVT16501 . . . WD PACKAGE SN74LVT16501...DGG OR DL PACKAGE (TOP VIEW)



description

The 'LVT16501 are 18-bit universal bus transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the devices operate in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.



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description (continued)

Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor. The minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN74LVT16501 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the input/output (I/O) pin count and functionality of standard small-outline packages in the same printed circuit board area.

The SN54LVT16501 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74LVT16501 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE†

	INP	UTS		OUTPUT
OEAB	LEAB	CLKAB	Α	В
L	Χ	Χ	Χ	Z
Н	Н	Χ	L	L
Н	Н	Χ	Н	Н
Н	L	\uparrow	L	L
Н	L	\uparrow	Н	н
Н	L	Н	Χ	B ₀ ‡
Н	L	L	Χ	в ₀ §

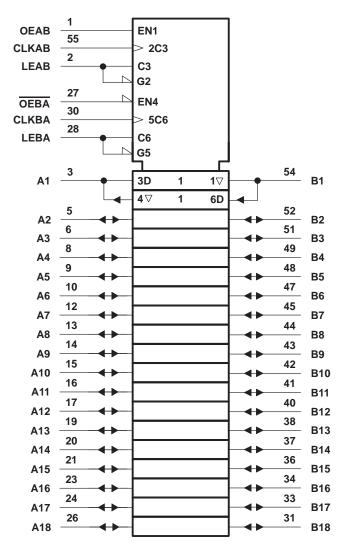
[†]A-to-B data flow is shown; B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.



[‡]Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low

[§] Output level before the indicated steady-state input conditions were established

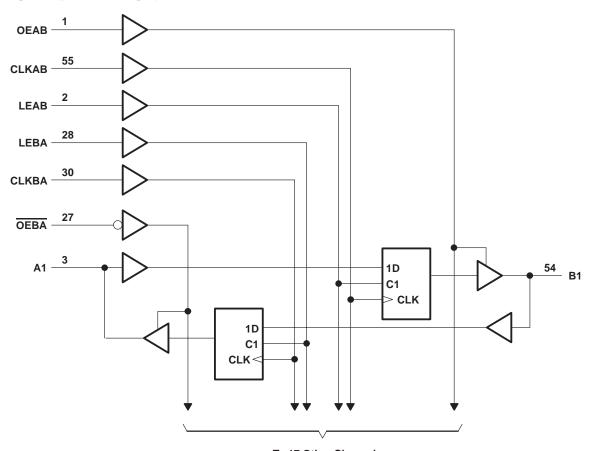
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –0.5 V to 4.6	V
Input voltage range, V _I (see Note 1)	V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1) -0.5 V to 7	V
Current into any output in the low state, IO: SN54LVT16501	٦A
SN74LVT16501 128 m	٦A
Current into any output in the high state, IO (see Note 2): SN54LVT16501	٦A
SN74LVT16501 64 m	٦A
Input clamp current, I_{IK} ($V_I < 0$)	٦A
Output clamp current, I_{OK} ($V_O < 0$)	٦A
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): DGG package	W
DL package	W
Storage temperature range, T_{stg}	°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the ABT Advanced BiCMOS Technology Data Book.



SN54LVT16501, SN74LVT16501 3.3-V ABT 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS147G - MAY 1992 - REVISED NOVEMBER 1996

recommended operating conditions (see Note 4)

			SN54LV	T16501	SN74LV	T16501	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage			5.5		5.5	V
IOH	High-level output current			-24		-32	mA
IOL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	RAMETER	TEST	CONDITIO	NIC .	SNS	54LVT16	501	SN7	4LVT16	501	UNIT
PAI	RAMETER	1531	CONDITIO	JN3	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNII
VIK		$V_{CC} = 2.7 \text{ V},$	I _I = -18 ı	mA			-1.2			-1.2	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	$I_{OH} = -1$	Ι00 μΑ	V _{CC} -0	.2		V _{CC} -0	.2		
\/a		$V_{CC} = 2.7 \text{ V},$	I _{OH} = -8	3 mA	2.4			2.4			V
VOH		V _{CC} = 3 V	I _{OH} = -2	24 mA	2						V
			I _{OH} = -3	32 mA				2			
		V _{CC} = 2.7 V	I _{OL} = 10	0 μΑ			0.2			0.2	
		VCC = 2.7 V	I _{OL} = 24	mA			0.5			0.5	
\/o.		I _{OL} = 16	i mA			0.4	0.4			V	
VOL			I _{OL} = 32	! mA			0.5			0.5	V
	V _{CC} = 3 V	I _{OL} = 48	s mA			0.55					
			I _{OL} = 64	mA				0.55			
	Control pins	$V_{CC} = 3.6 \text{ V},$	$\Lambda^{I} = \Lambda^{CC}$	or GND			±1			±1	
	Control pins	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5	V			10			10	μΑ
l _l		V _{CC} = 3.6 V	V _I = 5.5	V			120			20	
	A or B ports‡		AI = ACC	2			1			1	
			V _I = 0				- 5			– 5	
l _{off}		$V_{CC} = 0$,	V _I or V _O	= 0 to 4.5 V						±100	μΑ
1.0 . 0	A or B ports	V _{CC} = 3 V	$V_{I} = 0.8$	V	75			75			
^I I(hold)	A of B ports	ACC = 2 A	V _I = 2 V		-75			-75			μΑ
lozh		V _{CC} = 3.6 V,	VO = 3 \	/						1	μΑ
lozL		$V_{CC} = 3.6 \text{ V},$	$V_0 = 0.5$	5 V						-1	μΑ
				Outputs high			0.12			0.12	
ICC		$V_{CC} = 3.6 \text{ V},$ $V_{I} = V_{CC} \text{ or GND}$	$I_{O} = 0$,	Outputs low			5			5	mA
		AI = ACC OLGIAD		Outputs disabled			0.12			0.12	
ΔI _{CC} §		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$ Other inputs at V_{CC} o	One input at V _{CC} – 0.6 V, or GND				0.2			0.2	mA
Ci		V _I = 3 V or 0				3.5			3.5		pF
C _{io}		V _O = 3 V or 0				12			12		pF

[†] All typical values are at V_{CC} = 3.3 V, T_{A} = 25°C. ‡ Unused pins at V_{CC} or GND



[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

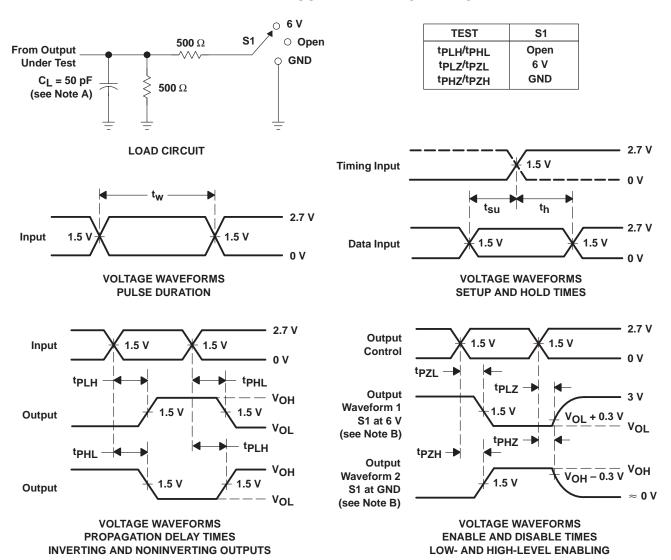
				SN54LV	T16501			SN74LV	T16501			
			V _{CC} =		V _{CC} =	2.7 V	V _{CC} =		V _{CC} =	2.7 V	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency		0	150	0	125	0	150	0	125	MHz	
	Pulse duration	LE high	3.3		3.3		3.3		3.3		ns	
t _W	Puise duration	CLK high or low	3.3		3.3		3.3		3.3		113	
	Setup time	A before CLKAB↑	1.6		2.1		1.6		2.1		-	
		B before CLKBA↑	1.6		2.1		1.6		2.1			
t _{su}		A or B before LE↓, CLK high	3.1		2.7		2.6		1.9		ns	
		A or B before LE↓, CLK low	2.6		2.0		2		1.3			
.	Hold time	A or B after CLK↑	2		2.1		2		2.1		no	
t _h	Hold lifte	A or B after LE↓	1.3		1.2		0.9	·	1.2		ns	

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)		SN54LV	T16501			SN7	4LVT16	501		
PARAMETER	FROM (INPUT)			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V_{CC} = 3.3 V \pm 0.3 V			V _{CC} = 2.7 V	
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX	
f _{max}			150		125		150			125		MHz
t _{PLH}	D or A	A or B	1.7	5.4		6.8	1.7	3	5.4		6.8	ns
^t PHL	B or A	AUID	1.6	6		7.8	1.6	3.2	5.9		7.7	115
t _{PLH}	LEBA or LEAB	A or B	2.3	7.3		9	2.3	4	7		8.5	ns
^t PHL	LEBA OF LEAD	AUIB	2.7	8.2		9.8	2.7	4.3	7.9		9.7	115
^t PLH	CLKBA or	A or B	2.5	8.3		9.7	2.5	4.1	7.9		9.2	ns
t _{PHL}	CLKAB	AUD	3.5	9.4		10.7	3.5	5.4	8.9		10.4	115
^t PZH	OFDA OF OFAR	A or B	1.2	5.1		6.1	1.2	3	5		5.9	ne
tPZL	OEBA or OEAB	AorB	1.5	5.9		7	1.5	3	5.8		6.9	ns
^t PHZ	OEBA or OEAB	A or B	2.7	7.5		8.5	2.7	4.6	7.4		8.3	ne
t _{PLZ}	OLDA OF OLAB	B A or B	2.8	6.8		7.5	2.8	4.7	6.7		7.2	ns

 $[\]uparrow$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \, \Omega$, $t_f \leq 2.5 \, \text{ns}$, $t_f \leq 2.5 \, \text{ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74LVT16501DGGR	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16501
SN74LVT16501DGGR.B	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16501

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

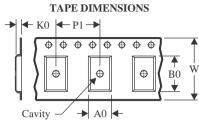
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

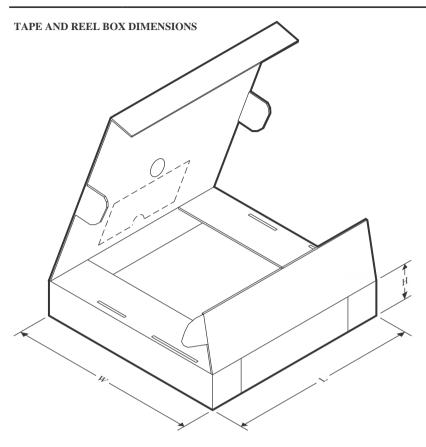


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT16501DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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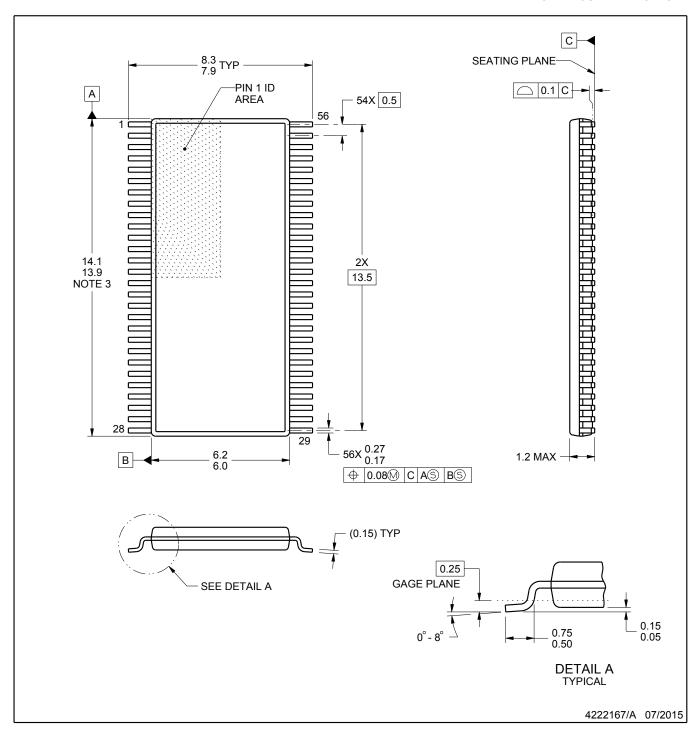


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LVT16501DGGR	TSSOP	DGG	56	2000	356.0	356.0	45.0	



SMALL OUTLINE PACKAGE



NOTES:

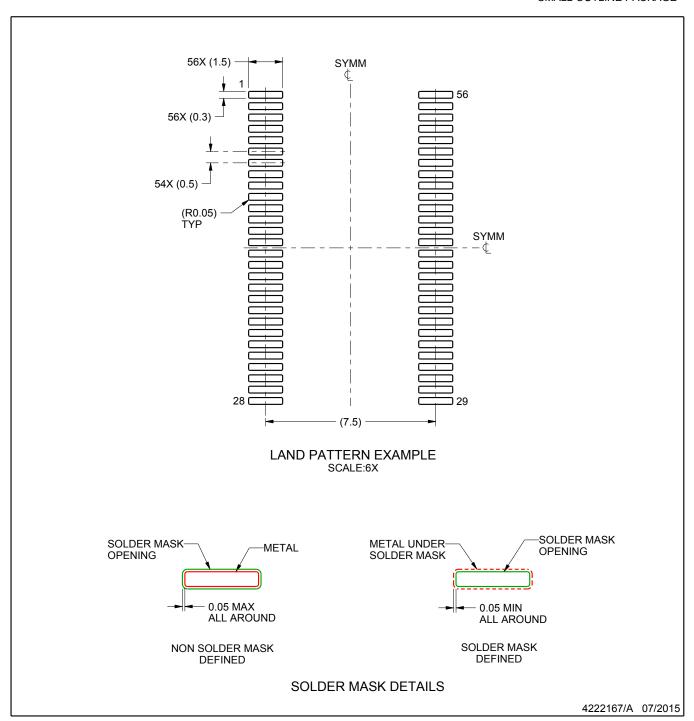
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

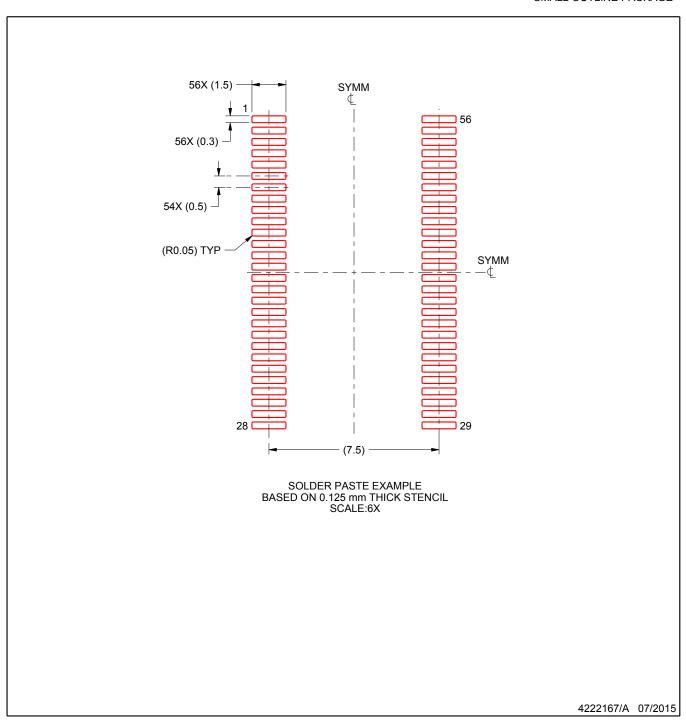


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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Last updated 10/2025